



### • General Description

It combines trench MOSFET technology with a low resistance package to provide extremely low  $R_{DS(ON)}$ .

### • Features

- Low  $R_{DS(ON)}$  to minimize conductive loss
- High GOX reliability
- Low Thermal resistance

### • Application

- BLDC Motor driver
- DC-DC
- Load switch

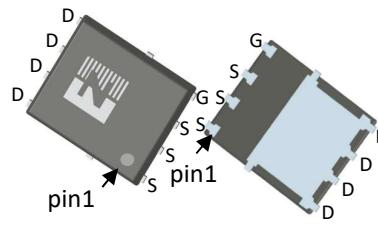
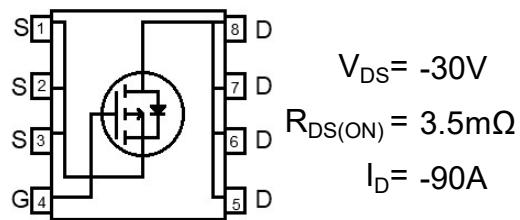
### • Ordering Information:

Part NO.	ZM035P03N
Marking	ZM035P03
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

### • Absolute Maximum Ratings ( $T_C=25^\circ\text{C}$ )

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	$V_{DS}$		-30	V
Gate-Source Voltage	$V_{GS}$		$\pm 20$	V
Continuous Drain Current	$I_D$	$T_C=25^\circ\text{C}$	-90	A
	$I_D$	$T_C=75^\circ\text{C}$	-87	A
	$I_D$	$T_C=100^\circ\text{C}$	-71	A
Pulsed Drain Current	$I_{DM}$	Pulsed; $t_p \leq 10 \mu\text{s}$ ; $T_{mb} = 25^\circ\text{C}$	-360	A
Total Power Dissipation	$P_D$	$T_C=25^\circ\text{C}$	89	W
Total Power Dissipation	$P_D$	$T_A=25^\circ\text{C}$	3.4	W
Operating Junction Temperature	$T_J$		-55 to +150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$		-55 to +150	$^\circ\text{C}$
Single Pulse Avalanche Energy	$E_{AS}$	$L=0.1\text{mH}$ , $V_{GS}=-10\text{V}$ , $R_g=25\Omega$ ,	180	mJ
		$L=0.5\text{mH}$ , $V_{GS}=-10\text{V}$ , $R_g=25\Omega$ ,	378	mJ
ESD Level (HBM)			CLASS 2	

### • Product Summary





## •Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub>		-	1.4	°C/W
Thermal resistance, junction-ambient①	R <sub>thJA</sub>		-	37	°C/W
Soldering temperature	T <sub>sold</sub>		-	260	°C

## •Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =-250uA	-30			V
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.2	-1.8	-2.5	V
Drain-Source Leakage Current	I <sub>DSS</sub>	V <sub>GS</sub> =0V, V <sub>DS</sub> = -30V			1.0	uA
Gate- Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> =±20V, V <sub>DS</sub> = 0V			100	nA
Static Drain-source On Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =-10V, I <sub>D</sub> = -24A		3.5	4.5	mΩ
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> = -12A		6	7.2	mΩ
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =-5V, I <sub>SD</sub> = -24A		20		s
Diode Forward Voltage	V <sub>FSD</sub>	V <sub>GS</sub> =0V, I <sub>SD</sub> = -24A			1.3	V

## •Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C <sub>iss</sub>	f = 1MHz, V <sub>DS</sub> =-25V	-	6670	-	pF
Output capacitance	C <sub>oss</sub>		-	664	-	
Reverse transfer capacitance	C <sub>rss</sub>		-	542	-	
Gate Resistance	R <sub>g</sub>	f = 1MHz	-	3		Ω
Total gate charge	Q <sub>g</sub>	V <sub>DD</sub> = -15V, I <sub>D</sub> = -10A, V <sub>GS</sub> = -10V	-	113	-	nC
	Q <sub>g(-4.5v)</sub>		-	61	-	
Gate - Source charge	Q <sub>gs</sub>	V <sub>GS</sub> = -10V	-	22	-	nC
Gate - Drain charge	Q <sub>gd</sub>		-	14	-	
Turn-ON Delay time	t <sub>D(on)</sub>	V <sub>GS</sub> =-10V, V <sub>DS</sub> =-15V, R <sub>G</sub> =3.3Ω, I <sub>D</sub> =-10A	-	27	-	ns
Turn-ON Rise time	t <sub>r</sub>		-	110	-	ns
Turn-Off Delay time	t <sub>D(off)</sub>		-	100	-	ns
Turn-Off Fall time	t <sub>f</sub>		-	42	-	ns
Reverse Recovery Time	t <sub>RR</sub>	V <sub>DD</sub> =-20V, dI <sub>S</sub> /dt = 100A/us, I <sub>S</sub> =-20A	-	205	-	ns
Reverse Recovery Charge	Q <sub>RR</sub>		-	467	-	nC



Fig.1 Gate-Charge Characteristics

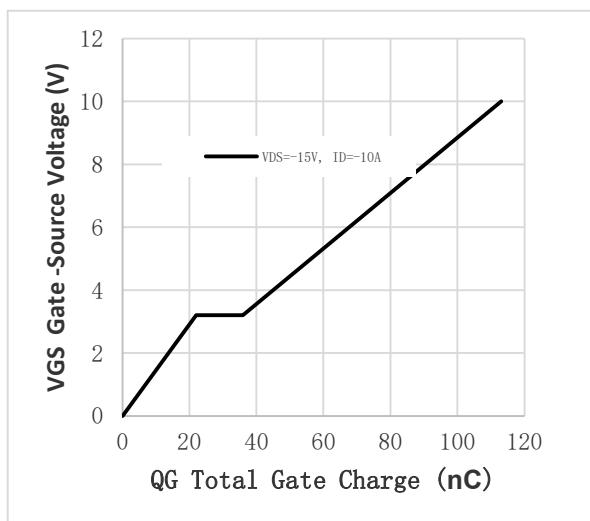


Fig.2 Capacitance Characteristics

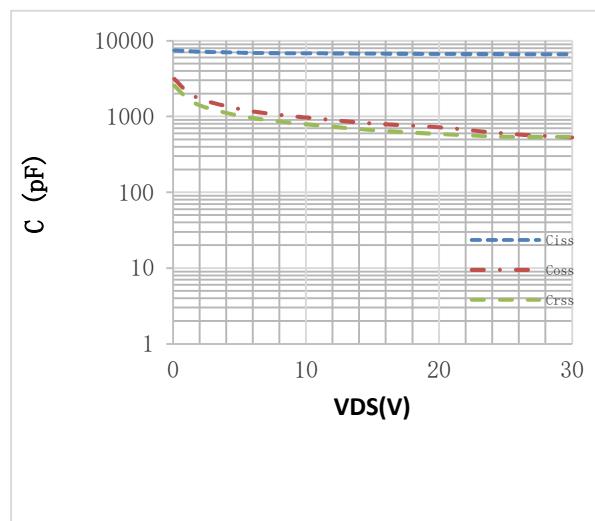


Fig.3 Power Dissipation

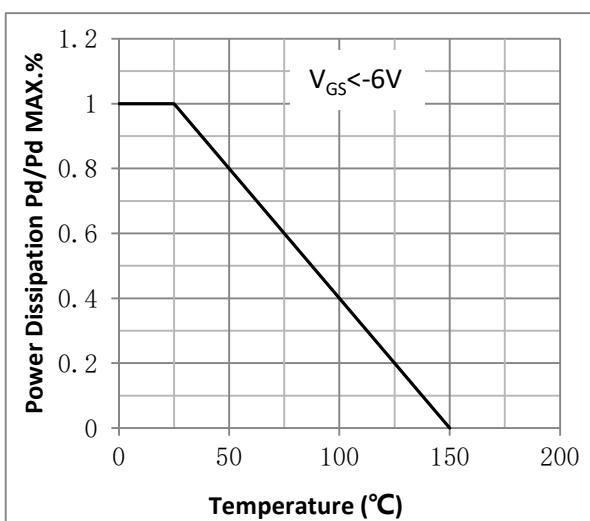


Fig.4 Typical output Characteristics

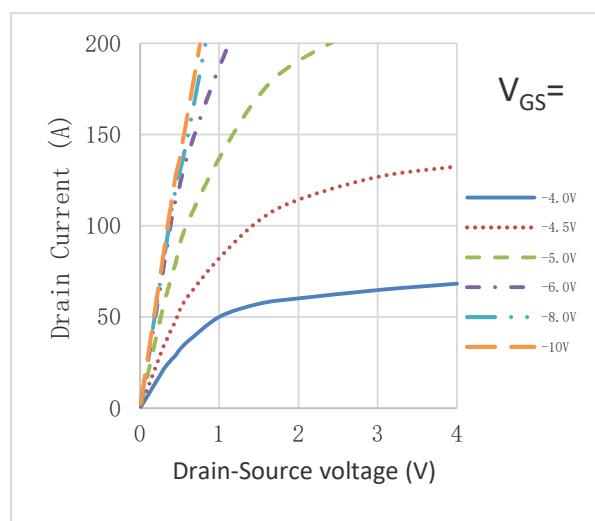


Fig.5 Threshold Voltage V.S Junction Temperature

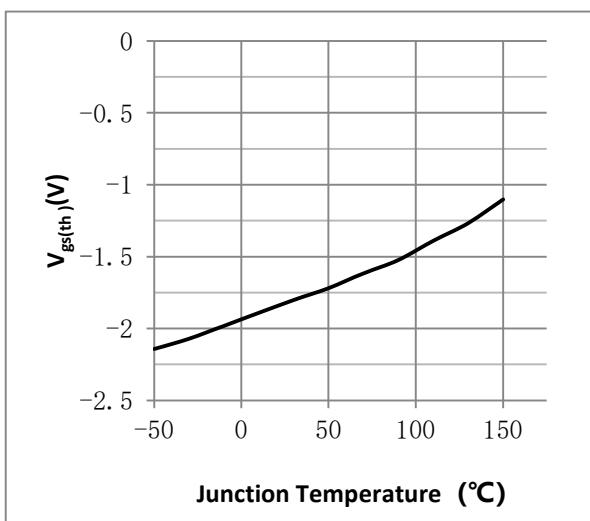


Fig.6 Resistance V.S Drain Current

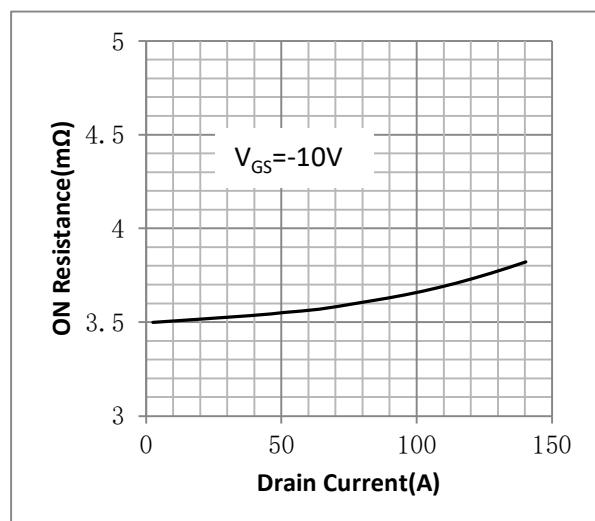




Fig.7 On-Resistance VS Gate Source Voltage

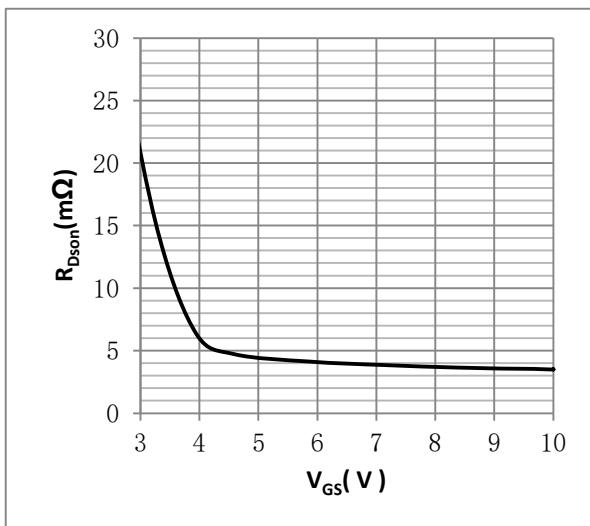


Figure 9. Diode Forward Voltage vs. Current

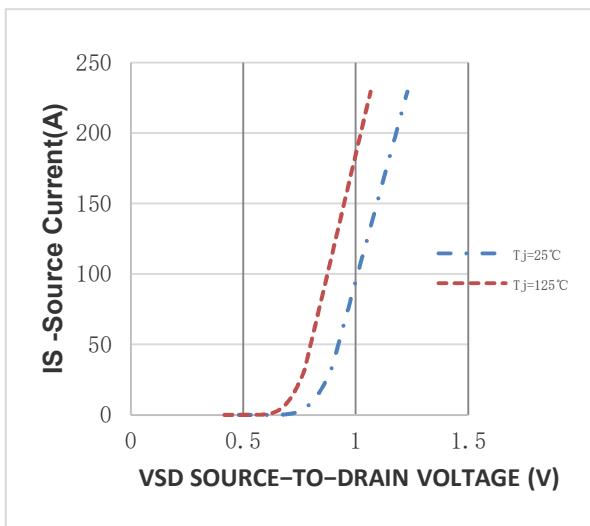


Fig.11 Safe Operating Area

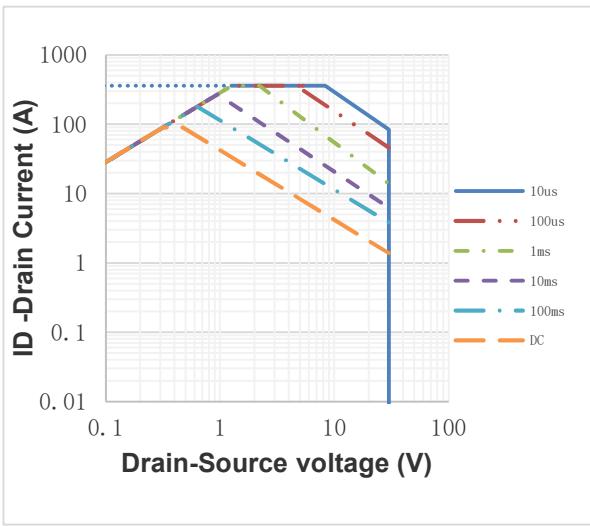


Fig.8 On-Resistance V.S Junction Temperature

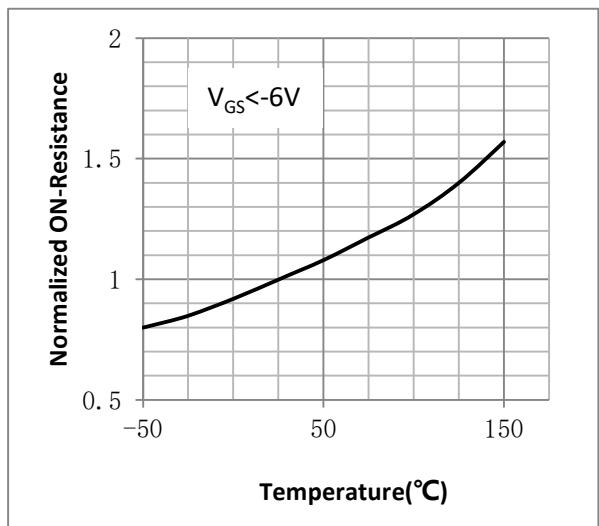
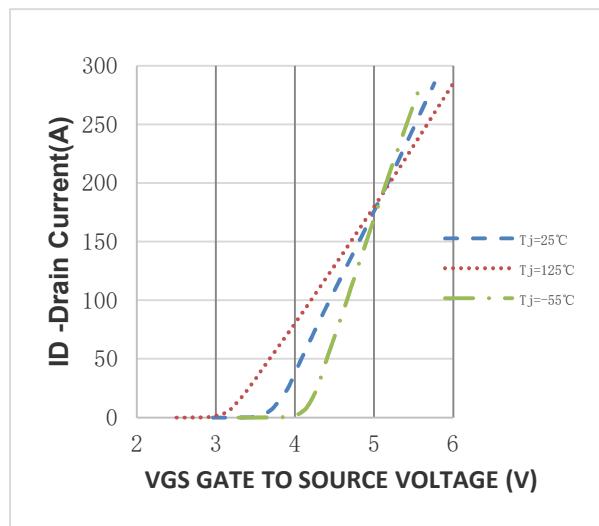
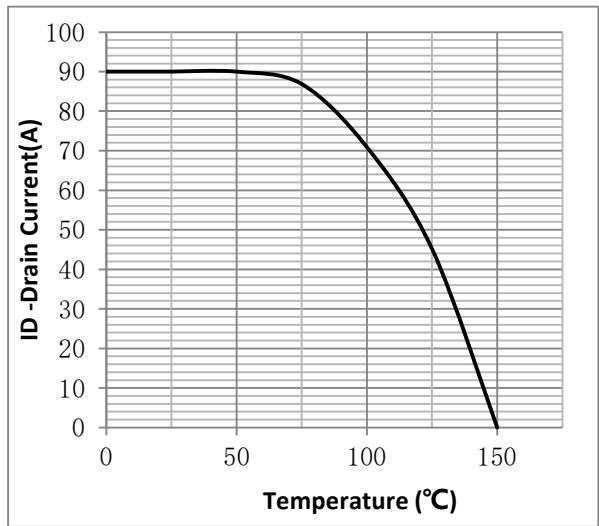
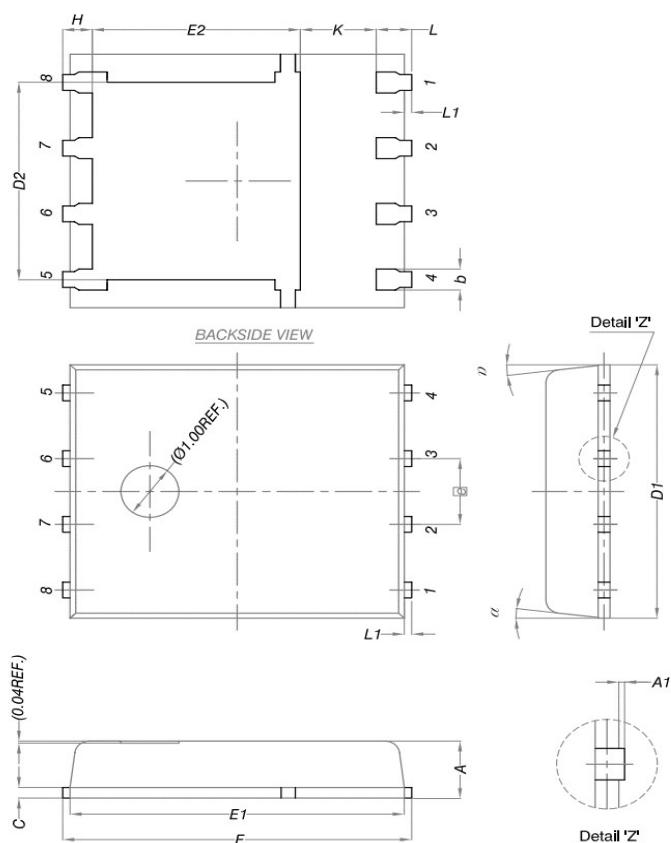


Figure 10. Transfer Characteristics

Fig.12 ID vs. Case Temperature<sup>②</sup>



## •DFN5\*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.33	0.41	0.51
C	0.20	0.25	0.30
D1	4.80	4.90	5.00
D2	3.61	3.81	3.96
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.38	3.58	3.78
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.20
$\alpha$	0°	-	12°

**Note:**

- ① Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ② Practically the current will be limited by PCB, thermal design and operating temperature. VGS=-10V.

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## Revision History

Version	Date	Change
A	2021.10.3	NEW
B	2024.1.20	Correct characteristic curves. Add dynamic characteristics
C	2024.5.13	Correct Qg chart VDS voltage.